

What is claimed is:

1. A semiconductor processing chamber comprising:
 - a chamber body having an open upper end;
 - a hinge coupled to the chamber body and having a fixed axis of rotation relative to the chamber body;
 - a lid assembly coupled to the chamber body by the hinge, the lid assembly rotatable between a first position sealing the open upper end and a second position clear of the upper end; and
 - a motor coupled to the hinge assembly for moving the lid assembly between at least the first position and the second position.
2. The semiconductor processing chamber of claim 1, wherein the hinge assembly further comprises:
 - one or more mounting brackets coupled to the lid assembly;
 - a shaft coupled to the mounting brackets; and
 - one or more bearing mounts rotatably coupled to the shaft.
3. The semiconductor processing chamber of claim 2, wherein the motor is coupled to the shaft.
4. The semiconductor processing chamber of claim 2, wherein the shaft is coplanar with the upper surface of the chamber body.
5. The semiconductor processing chamber of claim 2, wherein the bearing mounts are coupled to the chamber body, a frame circumscribing the chamber body or a processing platform having the chamber body coupled thereto.
6. The semiconductor processing chamber of claim 1, wherein the lid assembly further comprises a target and a magnetron.

7. The semiconductor processing chamber of claim 1 further comprising:
 - a plurality of first locating devices disposed between the lid assembly and the chamber body disposed proximate a shaft of the hinge assembly; and
 - a plurality of second locating devices disposed between the lid assembly and the chamber body, the second locating devices disposed outward of the first locating devices relative the shaft.
8. The semiconductor processing chamber of claim 7, wherein each of the first locating devices further comprises:
 - a pin and a bushing having a "C" shaped cross section.
9. The semiconductor processing chamber of claim 8, wherein each of the second locating devices further comprises:
 - a pin and a cylindrical bushing.
10. The semiconductor processing chamber of claim 8, wherein the pin is coupled to the lid assembly.
11. A semiconductor processing chamber comprising:
 - a chamber body having sidewalls and a bottom defining an interior volume;
 - a lid coupled to the chamber body and having a bottom movable between a first position enclosing the interior volume and a second position;
 - a target coupled to the bottom of the lid;
 - a first mounting bracket coupled to the lid assembly;
 - one or more bearing mounts coupled to the chamber body;
 - a shaft having a fixed position relative to the chamber body and lid assembly, the shaft coupled to the first mounting bracket and rotatably disposed through the bearing mounts; and
 - a motor coupled to at least one of the shaft or first mounting bracket for moving the lid assembly between at least the first position and the second position.

12. The semiconductor processing chamber of claim 11 further comprising:
a first bushing having a "C" shaped cross section disposed in the chamber body; and
a first pin disposed between the lid assembly and the chamber body wherein a portion of the first pin mates with the first bushing.
13. The semiconductor processing chamber of claim 11 further comprising:
a first bushing having a "C" shaped cross section disposed in the chamber body;
a first pin disposed between the lid assembly and the chamber body wherein a portion of the first pin mates with the first bushing;
a second bushing having a cylindrical cross section disposed in the chamber body outward of the first bushing relative to the shaft; and
a second pin disposed between the lid assembly and the chamber body wherein a portion of the second pin mates with the second bushing.
14. The semiconductor processing chamber of claim 11, wherein the shaft is coplanar with the upper surface of the chamber body.
15. The semiconductor processing chamber of claim 11, further comprising:
a second mounting bracket coupled to the lid assembly and the shaft;
and
a brace coupled between the first and second mounting brackets.
16. A semiconductor processing chamber comprising:
a chamber body having an open upper end;
a hinge coupled to the chamber body and having an axis of rotation disposed at a fixed location outward of the chamber body;
a lid assembly disposed at a radial distance to the axis of the hinge, the lid assembly rotatable about the axis of the hinge between a first position sealing the open upper end and a second position clear of the upper end; and
a motor coupled to the hinge assembly for moving the lid assembly between at least the first position and the second position.

17. The semiconductor processing chamber of claim 16, further comprising:
a physical vapor deposition target coupled to a bottom of the lid.
18. A physical vapor deposition chamber comprising:
a chamber body having sidewalls and a bottom defining an interior volume;
a lid coupled to the chamber body and having a bottom movable between a first position enclosing the interior volume and a second position;
a target coupled to the bottom of the lid;
one or more mounting brackets coupled to the lid assembly;
a shaft fixed to the mounting brackets;
one or more bearing mounts disposed on the chamber body and rotatably coupled to the shaft;
a motor coupled to at least one of the shaft or mounting brackets for moving the lid assembly between at least the first position and the second position;
a first bushing having a "C" shaped cross section disposed in the chamber body;
a first pin disposed between the lid assembly and the chamber body wherein a portion of the first pin mates with the first bushing;
a second bushing having a cylindrical cross section disposed in the chamber body outward of the first bushing relative to the shaft; and
a second pin disposed between the lid assembly and the chamber body wherein a portion of the second pin mates with the second bushing.